



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

OHMI *et al.*

Appln. No.: 09/678,741

Filed: October 4, 2000

Title: PLASMA PROCESSING APPARATUS

Confirmation No.: 9698

Group Art Unit: 1763

Examiner: CROWELL, ANNA M.

August 20, 2002

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AMENDMENT

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Hon. Commissioner of Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated April 25, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend claims 1-8 and 13-15 as follows:

*Sub
CIA*

1. (Amended) A plasma processing apparatus for applying a process to a substrate to be processed, the plasma processing apparatus comprising:

 a chamber of which interior can be depressurized,

 a gas supply system constructed and arranged to supply a gas to the chamber and an exhaust system configured and arranged to exhaust the gas supplied to the chamber and to depressurize the chamber;

 a part of a wall constituting the chamber being a flat plate dielectric material plate formed of a material which passes a microwave therethrough substantially without a loss;

 a flat plate dielectric material shower plate, which is formed of a material which passes a microwave therethrough substantially without a loss, being provided between the dielectric material plate and plasma excited in the chamber;

 a plurality of gas discharge holes being formed in the dielectric material shower plate so that at least a part of the gas supplied by the gas supply system is discharged through the

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03 FC:103